



Laser Writer

Heidelberg Instruments DWL 2000

Laser Pattern Generator



Description

The Heidelberg Instruments DWL 2000 Laser Pattern Generator uses a high resolution laser to expose photoresist for substrate patterning of features as small as 700 nm. The system can be used both for patterning chrome on glass photomasks and for maskless direct substrate writing. The laser writer can process substrates up to 200 mm in diameter and 7 mm thick. Standard processes include photomask patterning for use in both contact and stepper lithography.

Specifications / Capabilities

- Laser wavelength: 405 nm.
- Minimum feature size: 700 nm.
- Write speed: 110 mm² / min.
- Address grid: 20 nm.
- Patterning to substrate edge with optical autofocus.
- Allowed data formats: DXF, GDS-II, CIF, and Gerber.
- Alignment system for exposing patterns on existing structures.
- Closed loop environment system.

Supported Sample Sizes:

- Maximum wafer diameter: 200 mm (8 in).
- Maximum substrate thickness: 7 mm.
- Small pieces supported: Yes.
- Photomask blank sizes provided: 125 mm (5 inch) and 150 mm (6 inch).

Typical Applications:

- Micrometer and sub-micrometer lithography.
- Photomask patterning for:
 - Contact lithography.
 - Stepper lithography.
 - Direct substrate patterning (maskless lithography).

Link

<http://www.himt.de/>

<http://www.himt.de/index.php/dwl-2000.html>



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